SiI 164 PanelLink Transmitter Data Sheet

General Description

The SiI164 transmitter uses **PanelLink**® Digital technology to support displays ranging from VGA to UXGA resolutions (25 - 165Mpps) in a single link interface. The SiI164 transmitter has a highly flexible interface with either a 12-bit mode (½ pixel per clock edge) or 24-bit mode 1-pixel/clock input for true color (16.7 million) support. In 24-bit mode, the SiI164 supports single or dual edge clocking. In 12-bit mode, the SiI164 supports dual edge single clocking or single edge dual clocking. The SiI164 can be programmed though an I^2C interface. The SiI164 support Receiver and Hot Plug Detection.

PanelLink Digital technology simplifies PC design by resolving many of the system level issues associated with high-speed mixed signal design, providing the system designer with a digital interface solution that is quicker to market and lower in cost.

Features

- Scaleable Bandwidth: 25 - 165 Mega-pixels/sec (VGA to UXGA)
- Flexible Graphics Controller Interface: 12-bit (½ pixel) or 24-bit mode 1 pixel/clock inputs
- Flexible Input Clocking: Single clock single edge (24-bit), Single clock dual edge (12-/24-bit), Dual clock single edge (12-bit)
- I^2C Slave Programming Interface
- Low Voltage Interface: 3.3V with option for 1.0 to 1.8V
- Receiver Detection: Supports Hot Plug Detection
- De-skewing Option: varies clock to data timing
- Low Power: 3.3V core operation and power down mode
- Cable Distance Support: over 5m with twisted pair and fiber-optics ready
- Standards Compliant with DVI 1.0 (DVI is backwards compliant with VESA® P&D™ and DFP)

SiI164 Pin Diagram

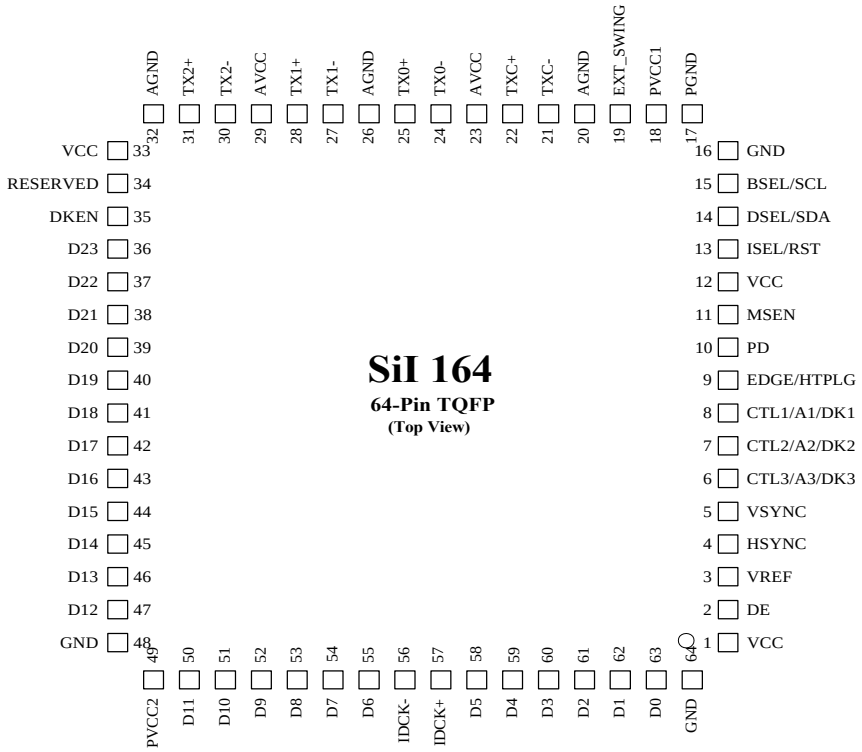
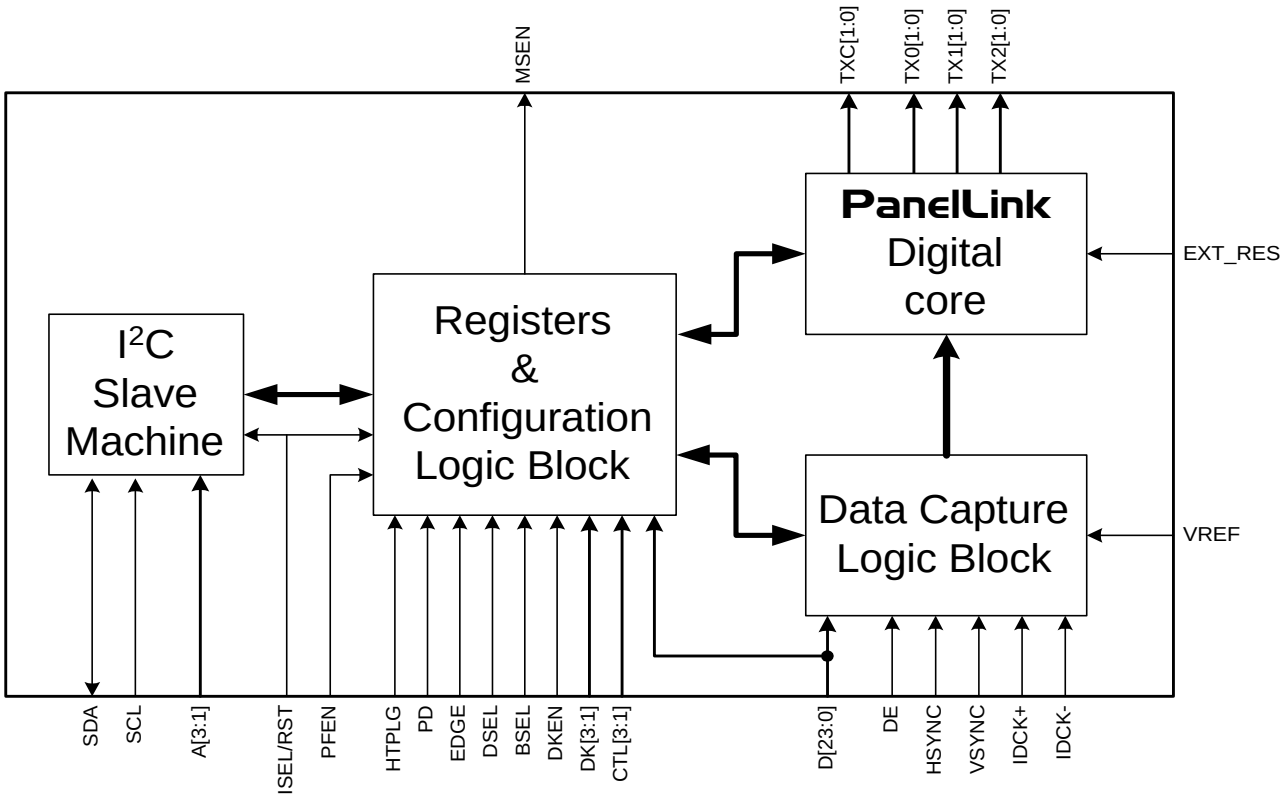


Figure 1. SiI 164 Pin Diagram

Functional Block Diagram



Electrical Specifications

Absolute Maximum Conditions

Symbol	Parameter	Min	Typ	Max	Units
V_{CC}	Supply Voltage 3.3V	-0.3		4.0	V
V_I	Input Voltage	-0.3		V_{CC}+ 0.3	V
V_O	Output Voltage	-0.3		V_{CC}+ 0.3	V
T_A	Ambient Temperature (with power applied)	-25		105	°C
T_{STG}	Storage Temperature	-40		125	°C
P_{PD}	Package Power Dissipation			1	W

Notes: [1] Permanent device damage may occur if absolute maximum conditions are exceeded.
[2] Functional operation should be restricted to the conditions described under Normal Operating Conditions.

Normal Operating Conditions

Symbol	Parameter	Min	Typ	Max	Units
V_{CC}	Supply Voltage	3.0	3.3	3.6	V
V_{CCN}	Supply Voltage Noise[1]			100	mV_{P-P}
T_A	Ambient Temperature (with power applied)	0	25	70	°C

Notes: [1]Guaranteed by design.

DC Digital I/O Specifications

Under normal operating conditions unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{IH}	High Swing High-level Input Voltage	$V_{REF} = V_{CC}$	2.0			V
V_{IL}	High Swing Low-level Input Voltage	$V_{REF} = V_{CC}$			0.8	V
V_{DDQ}[2]	Low Swing Voltage		1		1.8	V
V_{SH}	Low Swing High-level Input Voltage	$V_{REF} = V_{DDQ}/2$	$V_{DDQ}/2$ + 300mV			V
V_{SL}	Low Swing Low-level Input Voltage	$V_{REF} = V_{DDQ}/2$			$V_{DDQ}/2$ – 100mV	V
V_{CINL}	Input Clamp Voltage[1]	I_{CL} = -18mA			GND -0.8	V
V_{CIPL}	Input Clamp Voltage[1]	I_{CL} = 18mA			VCC + 0.8	V
I_{IL}	Input Leakage Current		-10		10	µA

Notes: [1]Guaranteed by design.
[2]V_{DDQ} Defines max voltage level of low swing input. It is not an actual input voltage.

DC Specifications

Under normal operating conditions unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{OD}	Differential Voltage	R_{LOAD} = 50Ω				
	Single ended peak to peak amplitude	$R_{EXT\ SWING}$ = 510Ω	510	550	590	mV
V_{DOH}	Differential High-level Output Voltage[1]			AVCC		V
V_{REF}	Input Reference Voltage	Low Swing	0.5	$V_{DDQ}/2$	0.9	V
		High Swing		VCC		V
I_{DOS}	Differential Output Short Circuit Current[1]	V_{OUT} = 0V			5	µA
I_{PD}	Power-down Current[2]	25°C Ambient, V_{cc} = 3.3V		0.2	1.0	mA
I_{CCT}	Transmitter Supply Current	DCLK = 165MHz, 1 pixel/clock mode, $R_{EXT\ SWING}$ = 510Ω				
		Worst Case Pattern[3] 25°C Ambient		85	120	mA

Notes: [1]Guaranteed by design.
[2]Assumes all inputs to the transmitter are not toggling.
[3]Black and white checkerboard pattern, each checker is one pixel wide.

AC Specifications

Under normal operating conditions unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Units
T_{CIP}	IDCK Period, 1-pixel/clock		6.06		40	ns
F_{CIP}	IDCK Frequency, 1-pixel/clock		25		165	MHz
T_{CIH}	IDCK High Time at 165MHz		2.0			ns
T_{CIL}	IDCK Low Time at 165MHz		2.0			ns
T_{IJIT}	Worst Case IDCK Clock Jitter[2,3]				2	ns
T_{SIDF}	Data, DE, VSYNC, HSYNC Setup Time to IDCK falling edge	Single Edge (DSEL = 0, DKEN = 0, EDGE = 0)	1.0			ns
T_{HIDF}	Data, DE, VSYNC, HSYNC Hold Time from IDCK falling edge	Single Edge (DSEL = 0, DKEN = 0, EDGE = 0)	0.9			ns
T_{SIDR}	Data, DE, VSYNC, HSYNC Setup Time to IDCK rising edge[1]	Single Edge (DSEL = 0, DKEN = 0, EDGE = 1)	1.0			ns
T_{HIDR}	Data, DE, VSYNC, HSYNC Hold Time from IDCK rising edge[1]	Single Edge (DSEL = 0, DKEN = 0, EDGE = 1)	0.9			ns
T_{SID}	Data, DE, VSYNC, HSYNC Setup Time to IDCK falling/rising edge[1]	Dual Edge (DSEL = 1, DKEN = 0, BSEL = 0)	0.6			ns
T_{HID}	Data, DE, VSYNC, HSYNC Hold Time from IDCK falling/rising edge[1]	Dual Edge (DSEL = 1, DKEN = 0, BSEL = 0)	1.3			ns
T_{DDF}	VSYNC, HSYNC Delay from DE falling edge[1]		$1T_{CIP}$			ns
T_{DDR}	VSYNC, HSYNC Delay to DE rising edge[1]		$1T_{CIP}$			ns
T_{HDE}	DE high time[1]	Vertical Blanking Only			$8191T_{CIP}$	ns
T_{LDE}	DE low time[1,4]	Vertical Blanking Only	$128T_{CIP}$			ns
T_{STEP}	De-skew step size increment	DKEN = 1		260		ps
S_{LHT}	Differential Swing Low-to-High Transition Time	C_{LOAD} = 5pF, R_{LOAD} = 50Ω, R_{EXT_SWING} = 510Ω	170	200	230	ps
S_{HLT}	Differential Swing High-to-Low Transition Time	C_{LOAD} = 5pF, R_{LOAD} = 50Ω, R_{EXT_SWING} = 510Ω	170	200	230	ps

Notes: [1]Guaranteed by design.
[2]Jitter can be estimated by 1) triggering a digital scope at the rising of input clock and 2) measuring the peak to peak time spread of the rising edge of the input clock at both 0.5µs and 1.0µs after the trigger.
[3]Actual jitter tolerance may be higher depending on the frequency of the jitter.
[4]DE Low time as defined as per DVI 1.0 Specification, Section 3.4 *Link Timing Requirements*.

Input Timing Diagrams

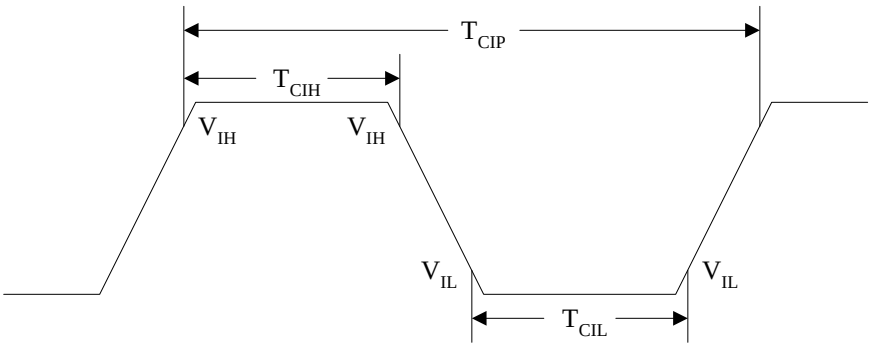


Figure 2. Clock Cycle/High/Low Times

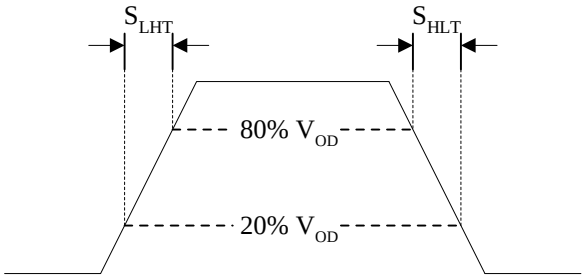


Figure 3. Differential Transition Times

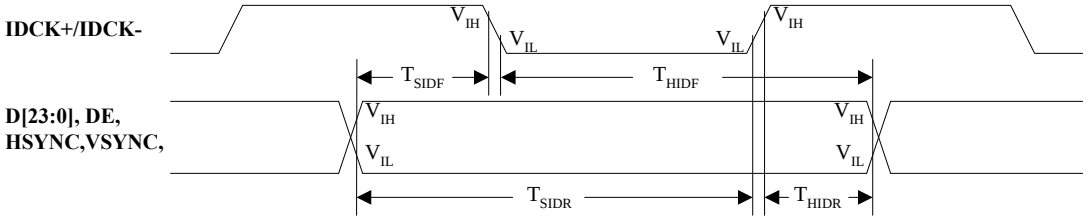


Figure 4. Control and Single-Edge-Data Setup/Hold Times to IDCK+/IDCK-

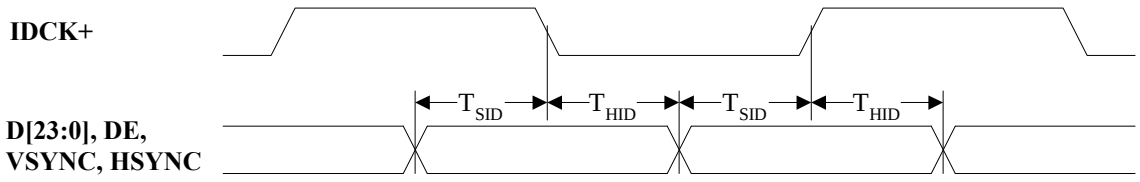


Figure 5. Dual Edge Data Setup/Hold Times to IDCK+

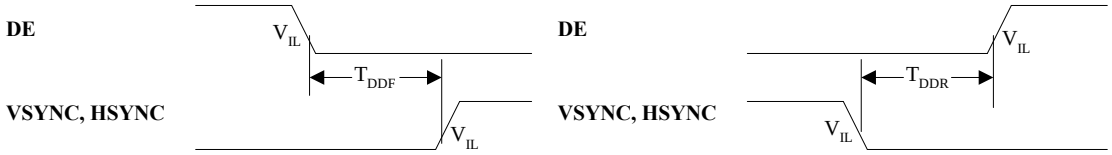


Figure 6. VSYNC, HSYNC Delay Times from/to DE

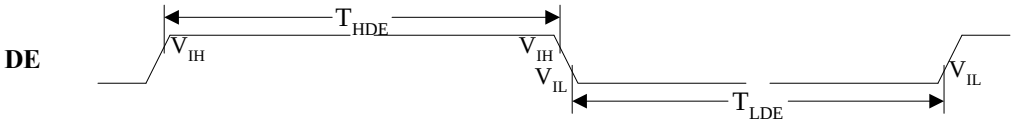


Figure 7. DE High/Low Times

Data Mapping

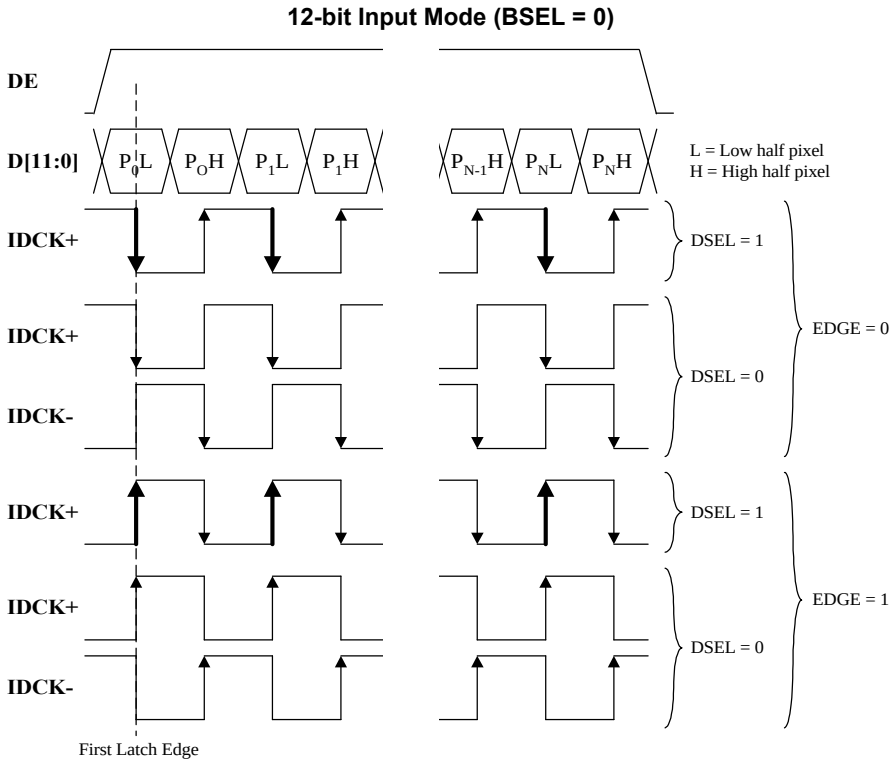


Figure 8. Logical Interface Options for 12-bit Mode

12-bit Mode Data Mapping

	P0		P1		P2	
	P0L	P0H	P1L	P1H	P2L	P2H
Pin Name	Low	High	Low	High	Low	High
D11	G0[3]	R0[7]	G1[3]	R1[7]	G2[3]	R2[7]
D10	G0[2]	R0[6]	G1[2]	R1[6]	G2[2]	R2[6]
D9	G0[1]	R0[5]	G1[1]	R1[5]	G2[1]	R2[5]
D8	G0[0]	R0[4]	G1[0]	R1[4]	G2[0]	R2[4]
D7	B0[7]	R0[3]	B1[7]	R1[3]	B2[7]	R2[3]
D6	B0[6]	R0[2]	B1[6]	R1[2]	B2[6]	R2[2]
D5	B0[5]	R0[1]	B1[5]	R1[1]	B2[5]	R2[1]
D4	B0[4]	R0[0]	B1[4]	R1[0]	B2[4]	R2[0]
D3	B0[3]	G0[7]	B1[3]	G1[7]	B2[3]	G2[7]
D2	B0[2]	G0[6]	B1[2]	G1[6]	B2[2]	G2[6]
D1	B0[1]	G0[5]	B1[1]	G1[5]	B2[1]	G2[5]
D0	B0[0]	G0[4]	B1[0]	G1[4]	B2[0]	G2[4]

Notes: [1] In the figure, clock edges represented by arrows signify the latching edge. The primary latch edge is indicated by the dark rows. The lower half of the pixel (L) is latched by the primary clock edge.
[2] Color Pixel Components: R = RED, G = GREEN, B = BLUE
[3] Bit significance within a color: [7:0] = [MSB:LSB]

24-bit Input Mode (BSEL = 1)

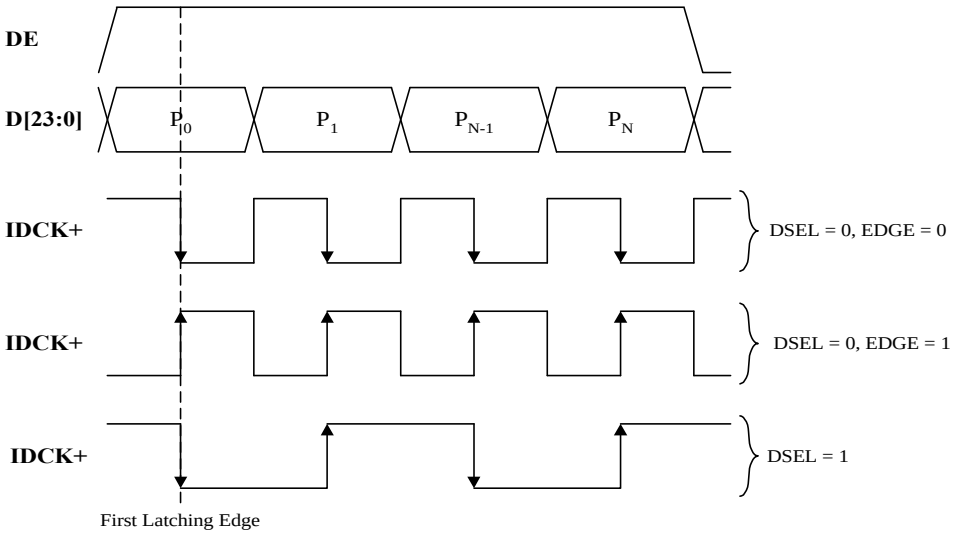


Figure 9. Logical Interface Options for 24-bit Mode

Note: In 24-bit Single Clock Dual Edge Mode, the SiI164 will look at the first clock edge (either falling or rising) after DE goes high to determine the first pixel data. EDGE pin has no affect in 24-bit Single Clock Dual Edge Mode.

24-bit Mode Data Mapping[1,2,3]

Pin Name	P0	P1	P2
D23	R0[7]	R1[7]	R2[7]
D22	R0[6]	R1[6]	R2[6]
D21	R0[5]	R1[5]	R2[5]
D20	R0[4]	R1[4]	R2[4]
D19	R0[3]	R1[3]	R2[3]
D18	R0[2]	R1[2]	R2[2]
D17	R0[1]	R1[1]	R2[1]
D16	R0[0]	R1[0]	R2[0]
D15	G0[7]	G1[7]	G2[7]
D14	G0[6]	G1[6]	G2[6]
D13	G0[5]	G1[5]	G2[5]
D12	G0[4]	G1[4]	G2[4]
D11	G0[3]	G1[3]	G2[3]
D10	G0[2]	G1[2]	G2[2]
D9	G0[1]	G1[1]	G2[1]
D8	G0[0]	G1[0]	G2[0]
D7	B0[7]	B1[7]	B2[7]
D6	B0[6]	B1[6]	B2[6]
D5	B0[5]	B1[5]	B2[5]
D4	B0[4]	B1[4]	B2[4]
D3	B0[3]	B1[3]	B2[3]
D2	B0[2]	B1[2]	B2[2]
D1	B0[1]	B1[1]	B2[1]
D0	B0[0]	B1[0]	B2[0]

Notes: [1] In the figure, clock edges represented by arrows signify the latching edge.
[2] Color Pixel Components: R = RED, G = GREEN, B = BLUE
[3] Bit significance within a color: [7:0] = [MSB:LSB]

Data De-skew

Input clock to data setup/hold time can be adjusted through the use of the de-skew feature. It should be noted that it is the clock that is being adjusted. When DKEN is HIGH, the configuration pins DK[3:1] or applicable I^2C registers can be used to vary the input setup/hold time by an amount T_{CD} given by the formula

T_{CD} = (DK[3:1] - 4) x 260psec.

Where:

T_{CD} is the amount setup/hold timing variation

DK[3:1] is the setting of the de-skew configuration pins or I^2C registers

This feature can be used in both 12-bit or 24-bit mode.

If DKEN is set LOW and the SiI164 is not in I^2C mode, the DK[3:1] inputs are ignored, and the default setting of T_{CD} = 0 is used.

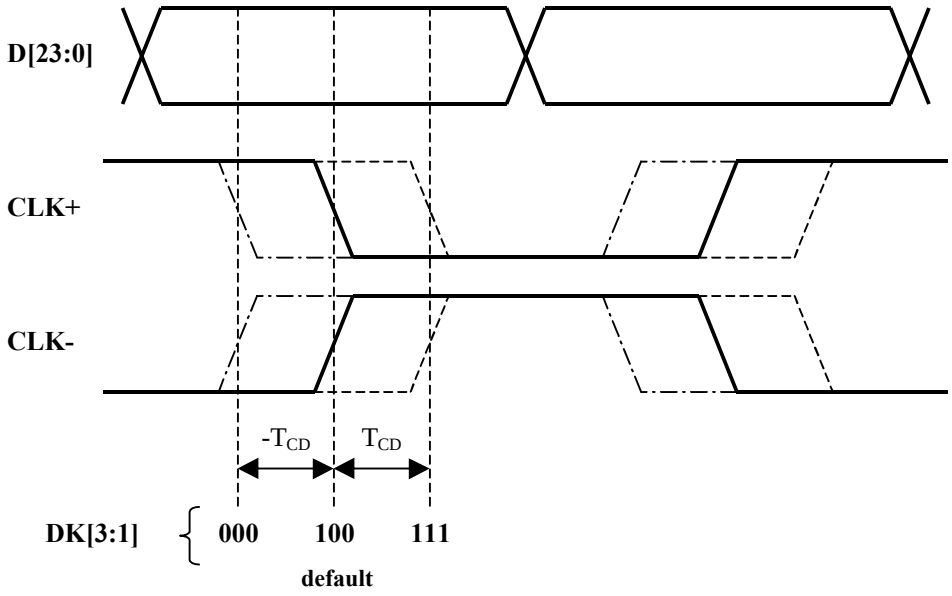


Figure 10. SiI164 De-skewing feature timing

Pins Descriptions

Input Pins

Pin Name	Pin #	Type	Description
D23-D12	36-47	In	Top half of 24-bit pixel bus. When BSEL = HIGH, this bus inputs the top half of the 24-bit pixel bus. When BSEL = LOW, these bits are not used to input pixel data. In this mode, the state of D[23:16] is input to the I^2C register CFG. This allows 8-bits of user configuration data to be read by the graphics controller through the I^2C interface (see I^2C register definition). D[15:12] are reserved for SiI use only and should be tied to GND when not in use.
D11–D0	50-55, 58-63	In	Bottom half of 24-bit pixel bus / 12-bit pixel bus input. When BSEL = HIGH, this bus inputs the bottom half of the 24-bit pixel bus. When BSEL = LOW, this bus inputs ½ a pixel (12-bits) at every latch edge (both falling and/or rising) of the clock.
IDCK+	57	In	Input Data Clock +.
IDCK-	56	In	Input Data Clock –. This clock is only used in 12-bit mode when dual edge clocking is turned off (DSEL = LOW). It is used to provide the ODD latching edges for dual clock single edge. If (BSEL = HIGH) or (DSEL = HIGH) this pin is unused and should be tied to GND.
DE	2	In	Data enable. This signal is high when input pixel data is valid to the transmitter and low otherwise. It is critical that this signal have the same setup/hold timing as the data bus.
HSYNC VSYNC	4 5	In In	Horizontal Sync input control signal. Vertical Sync input control signal.
CTL1/A1/DK1 CTL2/A2/DK2 CTL3/A3/DK3	8 7 6	In	The use of these multi-function inputs depends on the settings of ISEL and DKEN. These inputs are regular high-swing 3.3V CMOS level inputs. These pins contain weak pull-down resistors so that if left unconnected, they will be LOW. **ISEL = LOW, DKEN = LOW** General Purpose Input CTL[3:1] are active, for backward compatibility. These pins must be used to send DC signals only during the blanking time. **ISEL = LOW, DKEN = HIGH** DK[3:1] are active, these inputs are used to select the de-skewing setting for the input bus. **ISEL = HIGH, DKEN = X** A[3:1] are active, these bits are used to set the lower 3 bits of the I^2C device address.

Status Pin

Pin Name	Pin #	Type	Description
MSEN	11	Out	Monitor Sense. This pin is an open collector output. The behavior of this output depends on whether I^2C interface is enabled or disabled. **I^2C bus is disabled (ISEL = LOW)** A HIGH level indicates a powered on receiver is detected at the differential outputs. A LOW level indicates a powered on receiver is not detected. This function can only be used in DC-coupling systems. **I^2C bus is enabled (ISEL = HIGH)** The output is programmable through the I^2C interface (see I^2C register definitions). An external 5K pull-up resistor is required on this pin for systems without internal pull-up resistor.

Configuration/Programming Pins

Pin Name	Pin #	Type	Description
ISEL/RST	13	In	I^2C Interface Select. If HIGH, then the I^2C interface is active. If LOW, the I^2C is inactive and the chip configuration is read from the configuration strapping pins. This pin also acts as an asynchronous reset to the I^2C interface controller. The reset is active when this input is held LOW. Note: When the I^2C interface is active, DKEN must be set HIGH
BSEL/SCL	15	In	Input bus select / I^2C clock. This pin is an open collector input. If I^2C bus is enabled (ISEL = HIGH), then this pin is the I^2C clock input. If the I^2C is disabled (ISEL = LOW), then this pin selects the input bus width. **Input Bus Select :** HIGH selects 24-bit input mode LOW selects 12-bit input mode
DSEL/SDA	14	In	Dual edge clock select / I^2C Data. This pin is an open collector input. If I^2C bus is enabled (ISEL = HIGH), then this pin is the I^2C data line. If the I^2C bus is disabled (ISEL = LOW), then this pin selects whether single clock dual edge is used. **Dual edge clock select :** When HIGH, IDCK+ latches input data on both falling and rising clock edges. When LOW, IDCK+/IDCK- latches input data on only falling or rising clock edges. **In 24-/12-bit mode:** If HIGH (dual edge), IDCK+ is used to latch data on both falling and rising edges. If LOW (single edge), IDCK+ latches 1st half data and IDCK- latches 2nd half data.
EDGE/HTPLG	9	In	Edge select / Hot Plug input. If the I^2C bus is enabled (ISEL = HIGH), then this pin is used to monitor the "Hot Plug" detect signal (Please refer to the DVI™ or VESA® P&D™ and DFP standards). **NOTE:** This Input is ONLY 3.3V tolerant and has no internal debouncer circuit. If I^2C bus is disabled (ISEL = LOW), then this pin selects the clock edge that will latch the data. How the EDGE setting works depends on whether dual or single edge latching is selected : **Dual Edge Mode (DSEL = HIGH)** EDGE = LOW, the primary edge (first/even latch edge after DE is asserted) is the falling edge. EDGE = HIGH, the primary edge (first/odd latch edge after DE is asserted) is the rising edge. **Note:** In 24-bit single clock dual edge mode, EDGE is ignored. **Single Edge Mode (DSEL = LOW)** EDGE = LOW, the falling edge of the clock is used to latch data. EDGE = HIGH, the rising edge of the clock is used to latch data.
DKEN	35	In	De-Skewing enable. If I^2C bus is enabled (ISEL = HIGH), then this pin must be set to HIGH and DK[3:1] are ignored and the de-skewing increments are selected through the I^2C interface (see the I^2C register definitions). If I^2C bus is disabled (ISEL = LOW), then this pin enables the de-skewing increments to be read in through the DK[3:1] pins. When DKEN = LOW, then default de-skewing setting is used. When DKEN = HIGH, then DK[3:1] is used as the de-skewing setting. The de-skewing increments are 260psec.

Input Voltage Reference Pin

Pin Name	Pin #	Type	Description
VREF	3	Analog In	Input Reference Voltage. Selects the swing range of the digital parallel data inputs (D[23:0], DE, VSYNC, HSYNC, and IDCK). When VREF is HIGH, the digital parallel data inputs are normal high swing 3.3V inputs. When VREF is below 1.8V, the digital parallel data inputs are low swing inputs. In low swing mode, VREF must be set to ½ of V_{DDQ}.

Power Management Pin

Pin Name	Pin #	Type	Description
PD	10	In	Power Down (active LOW). A HIGH level indicates normal operation and a LOW level indicates power down mode. **During power down mode, digital input, output buffers and I^2C interface are NOT disabled. The PanelLink Digital core is powered down.** Note that when ISEL = HIGH, this pin should be tied LOW to ensure the chip is powered off when RESET is asserted.

Reserved

Pin Name	Pin #	Type	Description
RESERVED	34	In	Must be tied LOW for normal operation.

Differential Signal Data Pins

Pin Name	Pin #	Type	Description
TX0+ TX0- TX1+ TX1- TX2+ TX2-	25 24 28 27 31 30	Analog Analog Analog Analog Analog Analog	TMDS™ Low Voltage Differential Signal output data pairs.
TXC+ TXC-	22 21	Analog Analog	TMDS™ Low Voltage Differential Signal output clock pairs.
EXT_SWING	19	Analog	Voltage Swing Adjust. A resistor should tie this pin to AVCC. This resistance determines the amplitude of the voltage swing. For remote display applications, 510Ω is recommended. For notebook computers, 680Ω is recommended.

Power and Ground Pins

Pin Name	Pin #	Type	Description
VCC	1,12,33	Power	Digital VCC, must be set to 3.3V nominal.
GND	16,48,64	Ground	Digital GND.
AVCC	23,29	Power	Analog VCC, must be set to 3.3V nominal.
AGND	20,26,32	Ground	Analog GND.
PVCC1	18	Power	PLL Analog VCC, must be set to 3.3V nominal.
PVCC2	49	Power	PLL Analog VCC, must be set to 3.3V nominal.
PGND	17	Ground	PLL Analog GND.

I²C Registers

I²C Register Mapping

Addr.	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0x0	VND_IDL (RO)							
0x1	VND_IDH (RO)							
0x2	DEV_IDL (RO)							
0x3	DEV_IDH (RO)							
0x4	DEV_REV (RO)							
0x5	***RSVD[7:0] (RO)***							
0x6	FRQ_LOW (RO)							
0x7	FRQ_HIGH (RO)							
0x8	***RSVD[1:0]***		VEN (R/W)	HEN (R/W)	DSEL (RW)	BSEL (RW)	EDGE (RW)	PD (RW)
0x9	VLOW (RO)	MSEL[2:0] (RW)			TSEL (RW)	RSEN (RO)	HTPLG (RO)	MDI (RW)
0xA	DK[3:1] (RW)			DKEN (RW)	CTL[3:1] (RW)			***RSVD (RW)***
0xB	CFG[7:0] (D[23:16]) (RO)							
0xC	***VDJK[7:0] (RW) Must be set to "89h" for normal operation.***							
0xD	***RSVD[3:0] (RW)***				***RSVD[3:0] (RO)***			
0xE	***RSVD[7:0] (RW)***							
0xF	***RSVD[7:0] (RW)***							

Notes: [1] All values are Bit 7 [MSB] and Bit 0 [LSB].
[2] RW = Read/Write register, RO = Read Only register.
[3] RSVD = Reserved register. It is available for future use by Silicon Image, Inc.
[4] Values in ***Bold/Italics*** are for Silicon Image, Inc.
[5] Any read/write register that is RESERVED will require that the user always write the SiI recommended values.
[6] There is no default value on RESET except for PD and MSEL. All registers must be written at least once before normal operation can occur.
[7] All other registers do not retain their values after a RESET except for PD and MSEL.
[8] **Note that register 0xC must be set to "89h" for normal operation.**

I²C Register Definitions

Register Name	Access	Description
VND_IDL	RO	Vendor ID Low byte (01h)
VND_IDH	RO	Vendor ID High byte (00h)
DEV_IDL	RO	Device ID Low byte (06h)
DEV_IDH	RO	Device ID High byte (00h)
DEV_REV	RO	Device Revision (00h)
FRQ_LOW	RO	Low frequency limit at 1-pixel/clock mode (MHz) (19h)
FRQ_HIGH	RO	High frequency limit at 1-pixel/clock mode MHz minus 65MHz (MHz) (64h)
PD	RW	Power Down mode(same function as PD pin) 0 – Power Down (Default after RESET) 1 – Normal operation
EDGE	RW	Edge Select (same function as EDGE pin) 0 – Input data is falling edge latched (falling edge latched first in dual edge mode) 1 – Input data is rising edge latched (rising edge latched first in dual edge mode)
BSEL	RW	Input Bus Select (same function as BSEL pin) 0 – Input data bus is 12-bits wide 1 – Input data bus is 24-bits wide
DSEL	RW	Dual Edge Clock Select (same function as DSEL pin) 0 – Input data is single edge latched 1 – Input data is dual edge latched
HEN	RW	Horizontal Sync Enable: 0 – HSYNC input is transmitted as fixed LOW 1 – HSYNC input is transmitted as is
VEN	RW	Vertical Sync Enable: 0 – VSYNC input is transmitted as fixed LOW 1 – VSYNC input is transmitted as is
MDI	RW	Monitor Detect Interrupt 0 – Detection signal has changed logic level (write one to this bit to clear) 1 – Detection signal has not changed state
HTPLG	RO	Hot Plug Detect input, the state of HTPLG pin can be read from this bit
RSEN	RO	This bit is HIGH if a powered on receiver is connected to the transmitter outputs, LOW otherwise. This function is only available for use in DC-coupled systems.
TSEL	RW	Interrupt Generation Method 0 – Interrupt bit (MDI) is generated by monitoring RSEN pt bit (MDI) is generated by monitoring HTPLG
MSEL[2:0]	RW	Select source of the MSEN output pin 000 – Force MSEN outputs high (disabled – default after RESET) 001 – Outputs the MDI bit (interrupt) 010 – Output the RSEN bit (receiver detect) 011 – Outputs the HTPLG bit (hot plug detect)
VLOW	RO	This bit is a 1 if the VREF signal indicates low swing inputs. It is a 0 if VREF indicates high swing inputs
CTL[3:1]	RW	General purpose inputs (same as CTL[3:1] pins)
CFG[7:0]	RO	Contains state of inputs D[23:16]. These pins can be used to provide user selectable configuration data through the I²C bus. Only available in 12-bit mode
VDJK[7:0]	RW	**Must be set to "89h" for normal operation**

I²C Register Definitions (cont'd)

Register Name	Access	Description
DK[3:1]	RW	De-Skewing Setting. Increment 260psec. 000 : 1 step -> minimum setup / maximum hold 001 : 2 step 010 : 3 step 011 : 4 step 100 : 5 step -> default 101 : 6 step 110 : 7 step 111 : 8 step -> maximum setup / minimum hold
DKEN	RW	De-Skewing Enable through DK[3:1] bits. HIGH when enabled, LOW otherwise.

I²C Slave Interface

The SiI164 slave state machine does not require an internal clock and supports only byte read and write (see Figures below). Page mode is not supported. The 7-bit binary address of the I²C machine is "0111 $A_3A_2A_1X$", where A[3:1] are pin programmable or set to "000" by default.

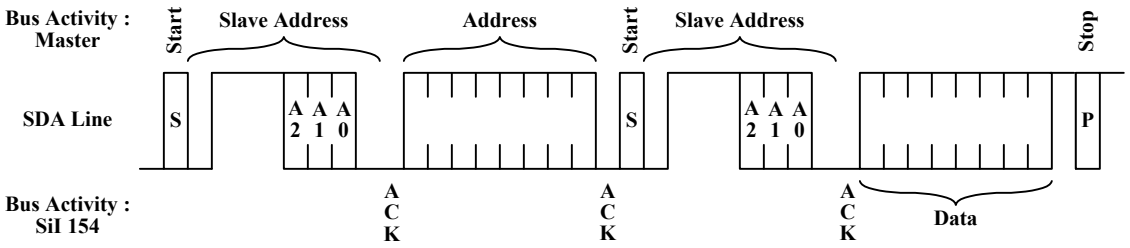


Figure 11. I²C Byte Read

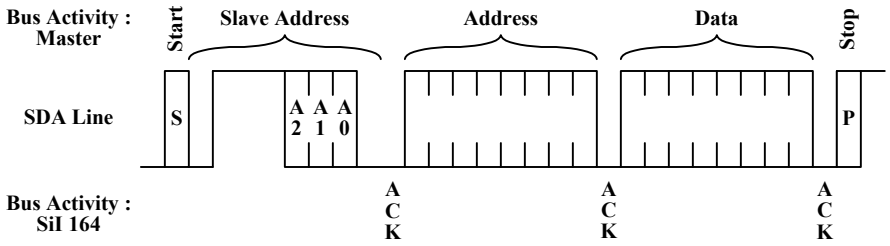


Figure 12. I²C Byte Write

RESET Description

The input pin ISEL/RST serves as an asynchronous RESET (active LOW) for the I^2C slave controller in I^2C mode. The programming registers, that are accessible over the I^2C bus, do not retain their previous values during and after the RESET. Registers PD and MSEL[2:0] are both disabled after RESET. All of the I^2C registers must be manually set to ensure proper operation. The minimum low time for proper RESET is T_{CIP}. The state of these bits is set during the RESET period according to the following rules:

- **After a RESET, the SiI164 will be turned OFF.** When RESET is asserted, the SiI164 power down control bit, PD, is forced LOW. When the SiI164 comes out of RESET (ISEL/RST is set HIGH), the SiI164 will be turned OFF. To turn the SiI164 back ON, the PD bit must be set HIGH over the I^2C bus.

- **After a RESET, MSEN output is disabled.** When RESET is asserted, MSEN[2:1] is forced to '000'. This causes the MSEN output to be tri-stated.

Package Dimensions

64-pin TQPF Package Dimensions

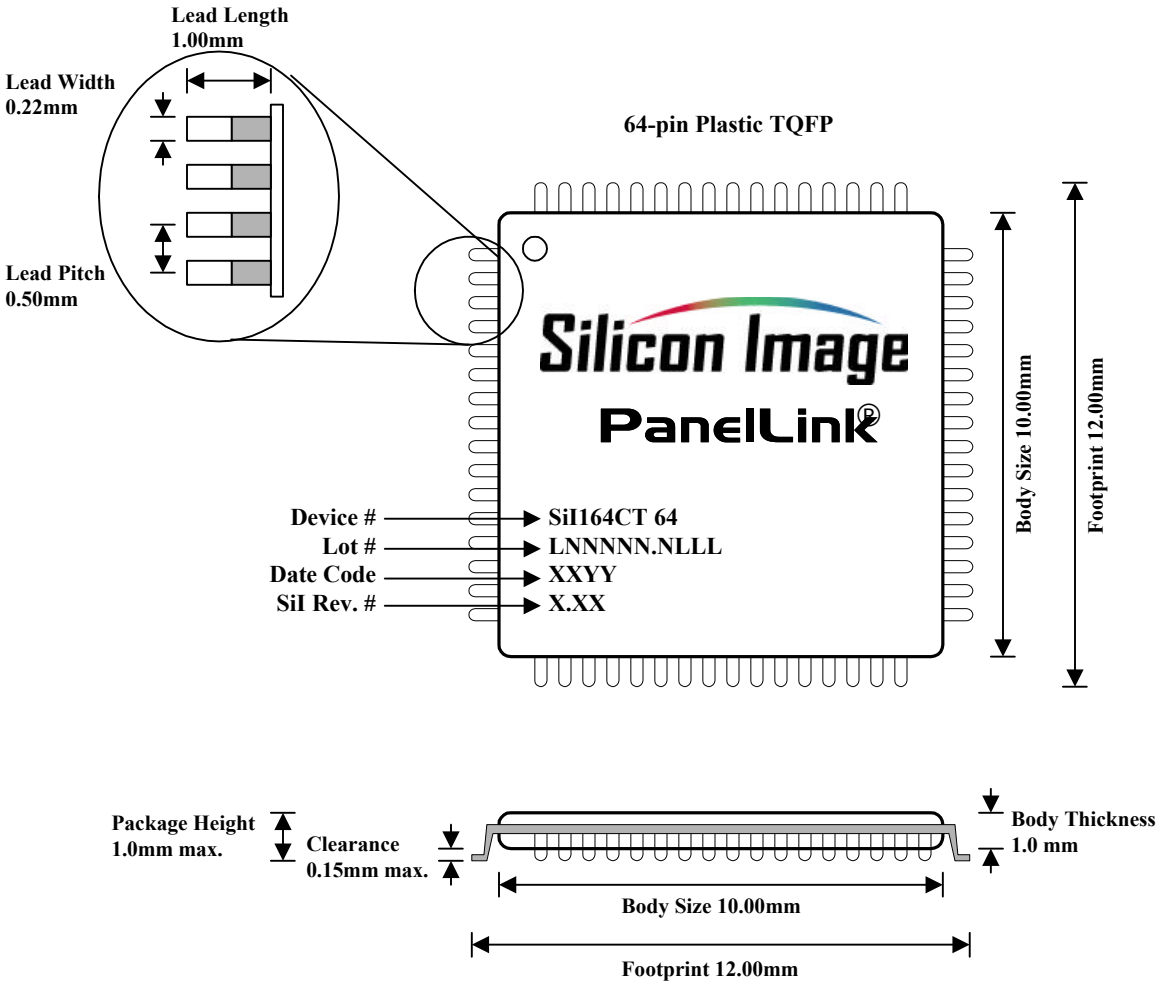


Figure 13. SiI164 Package Diagram

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Ordering Information

Part Number: SiI164CT64

Revision History

Revision	Date	Comment
0.1	6/99	First Draft
0.8	7/99	Preliminary release
A	3/00	Full release

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